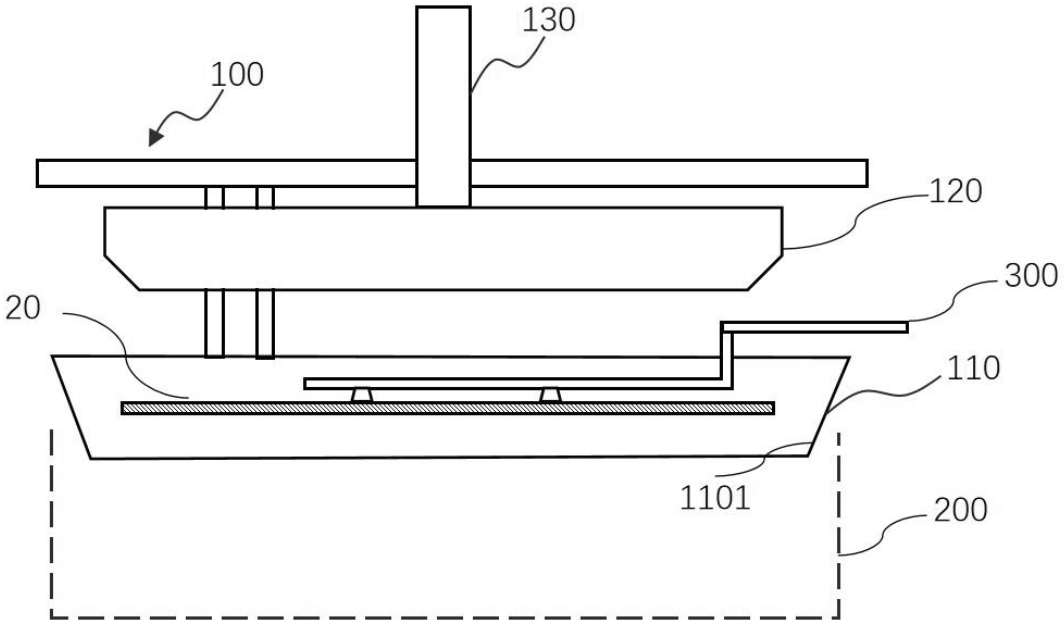


FIG 1

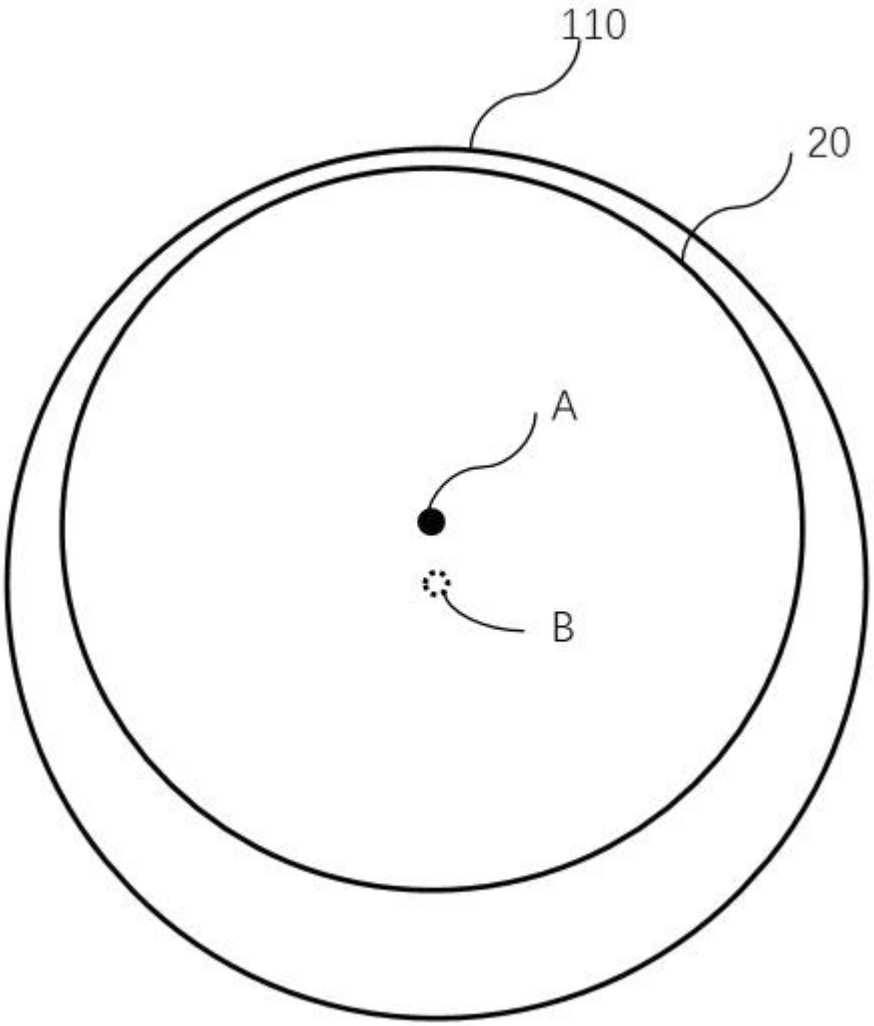


FIG 2a

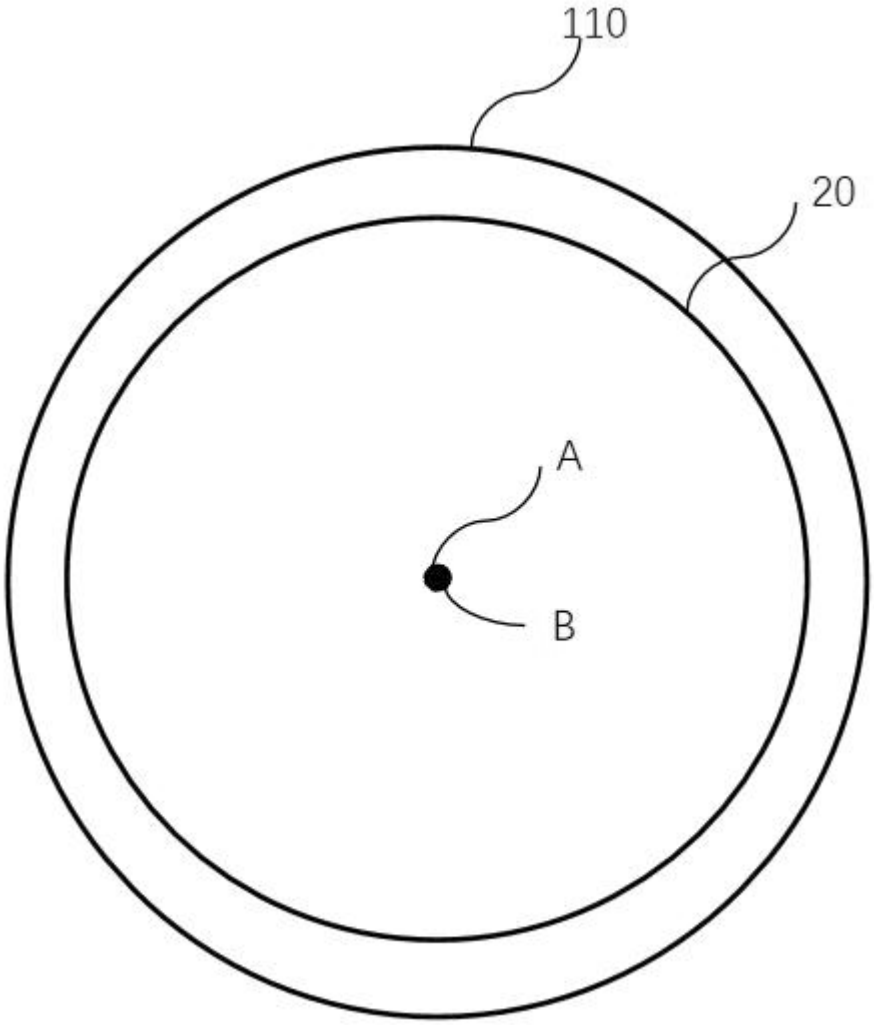


FIG 2b

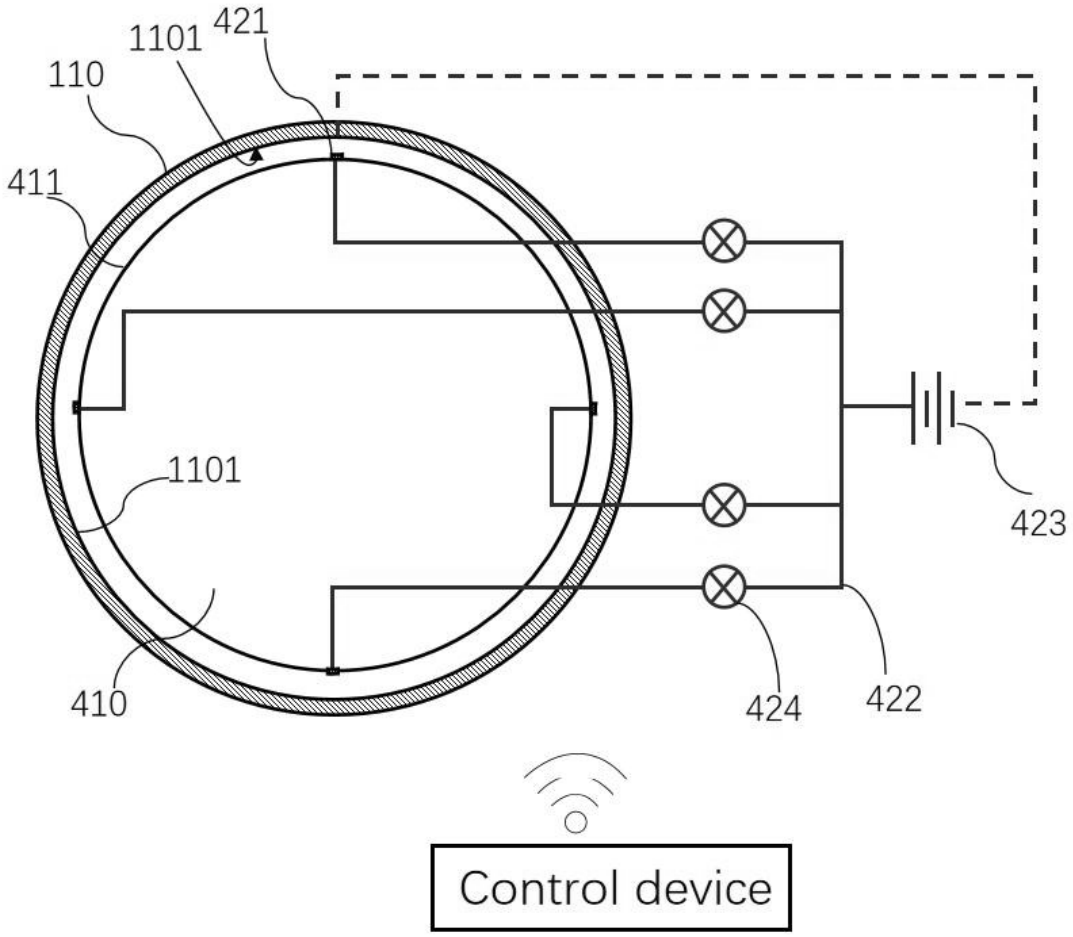


FIG 3

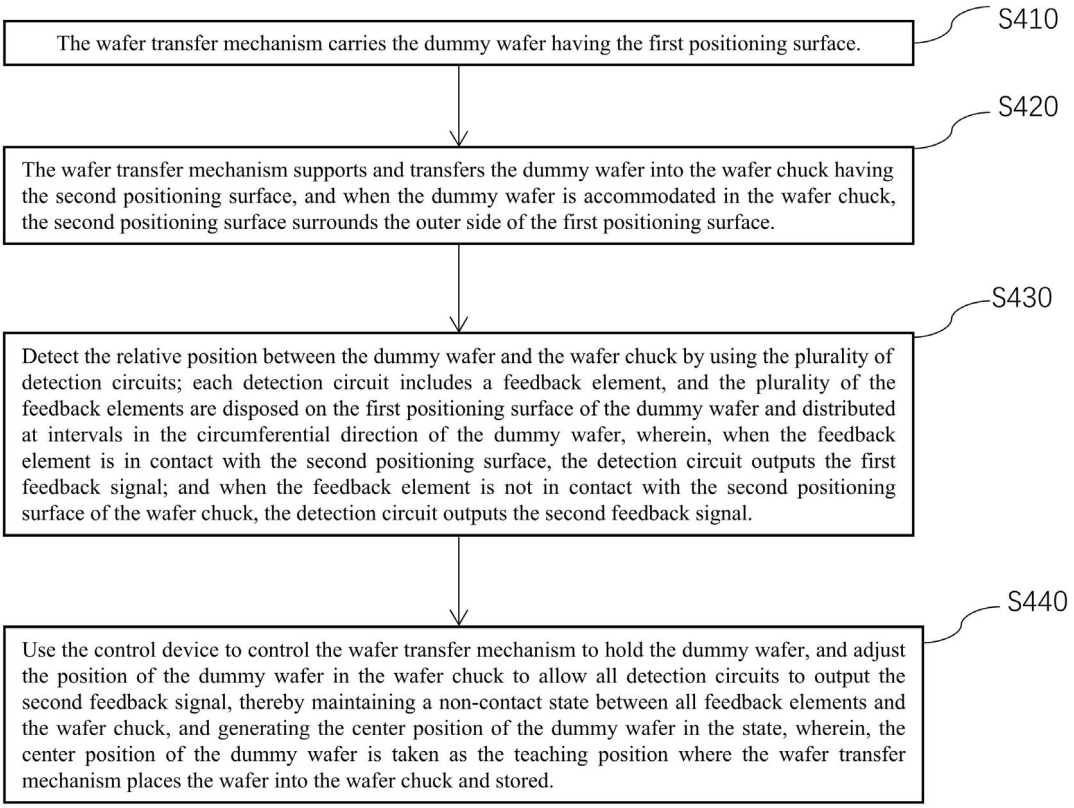

S410
The wafer transfer mechanism carries the dummy wafer having the first positioning surface.
S420
The wafer transfer mechanism supports and transfers the dummy wafer into the wafer chuck having the second positioning surface, and when the dummy wafer is accommodated in the wafer chuck, the second positioning surface surrounds the outer side of the first positioning surface.
S430
Detect the relative position between the dummy wafer and the wafer chuck by using the plurality of detection circuits; each detection circuit includes a feedback element, and the plurality of the feedback elements are disposed on the first positioning surface of the dummy wafer and distributed at intervals in the circumferential direction of the dummy wafer, wherein, when the feedback element is in contact with the second positioning surface, the detection circuit outputs the first feedback signal; and when the feedback element is not in contact with the second positioning surface of the wafer chuck, the detection circuit outputs the second feedback signal.
S440
Use the control device to control the wafer transfer mechanism to hold the dummy wafer, and adjust the position of the dummy wafer in the wafer chuck to allow all detection circuits to output the second feedback signal, thereby maintaining a non-contact state between all feedback elements and the wafer chuck, and generating the center position of the dummy wafer in the state, wherein, the center position of the dummy wafer is taken as the teaching position where the wafer transfer mechanism places the wafer into the wafer chuck and stored.

FIG 4

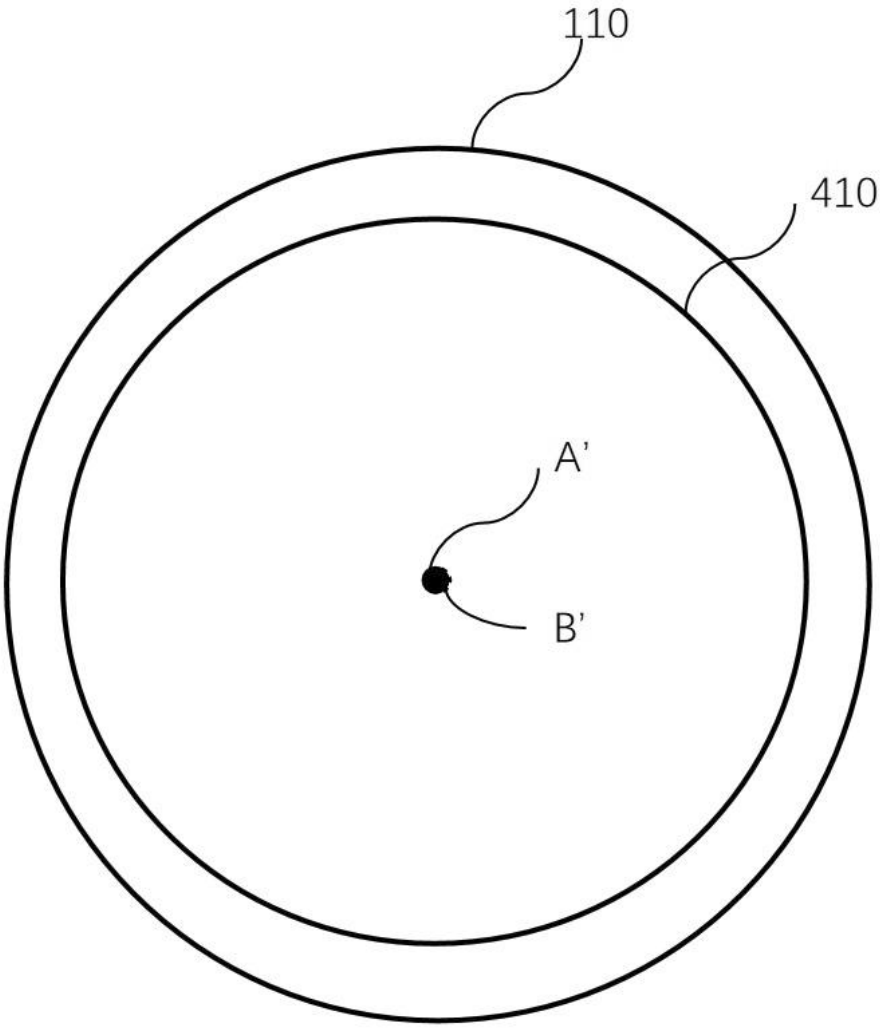


FIG 5

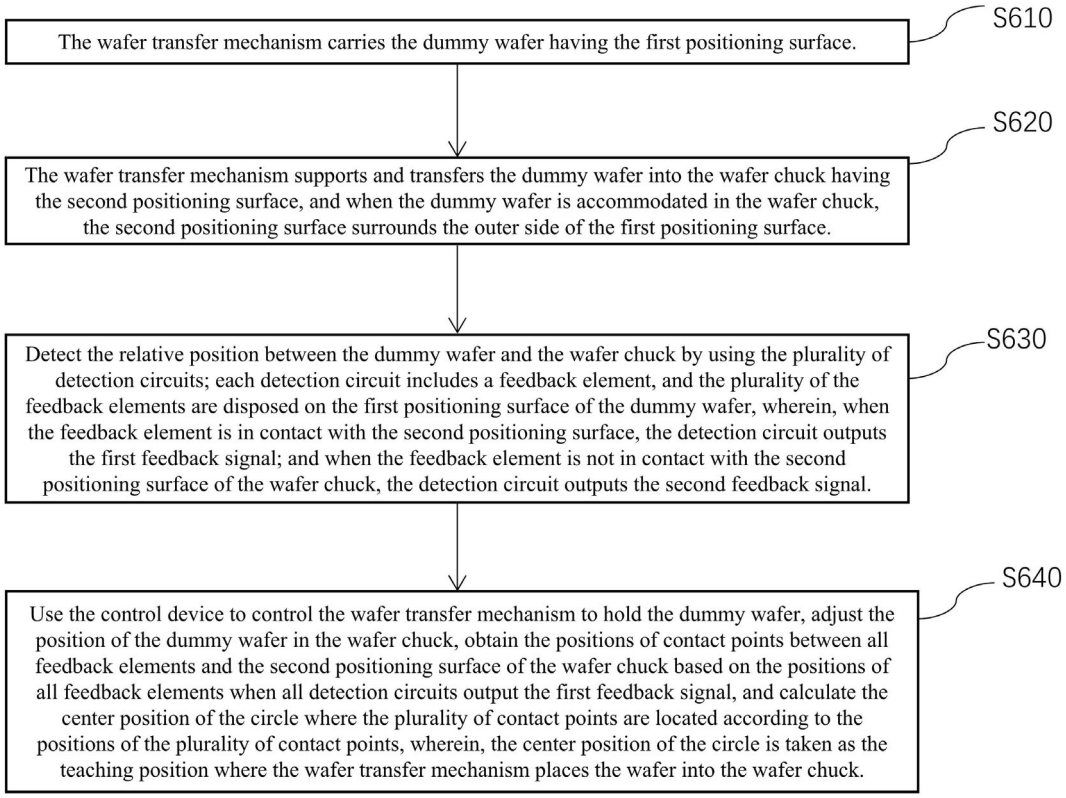

The wafer transfer mechanism carries the dummy wafer having the first positioning surface.
S610
The wafer transfer mechanism supports and transfers the dummy wafer into the wafer chuck having the second positioning surface, and when the dummy wafer is accommodated in the wafer chuck, the second positioning surface surrounds the outer side of the first positioning surface.
S620
Detect the relative position between the dummy wafer and the wafer chuck by using the plurality of detection circuits; each detection circuit includes a feedback element, and the plurality of the feedback elements are disposed on the first positioning surface of the dummy wafer, wherein, when the feedback element is in contact with the second positioning surface, the detection circuit outputs the first feedback signal; and when the feedback element is not in contact with the second positioning surface of the wafer chuck, the detection circuit outputs the second feedback signal.
S630
Use the control device to control the wafer transfer mechanism to hold the dummy wafer, adjust the position of the dummy wafer in the wafer chuck, obtain the positions of contact points between all feedback elements and the second positioning surface of the wafer chuck based on the positions of all feedback elements when all detection circuits output the first feedback signal, and calculate the center position of the circle where the plurality of contact points are located according to the positions of the plurality of contact points, wherein, the center position of the circle is taken as the teaching position where the wafer transfer mechanism places the wafer into the wafer chuck.
S640

FIG 6

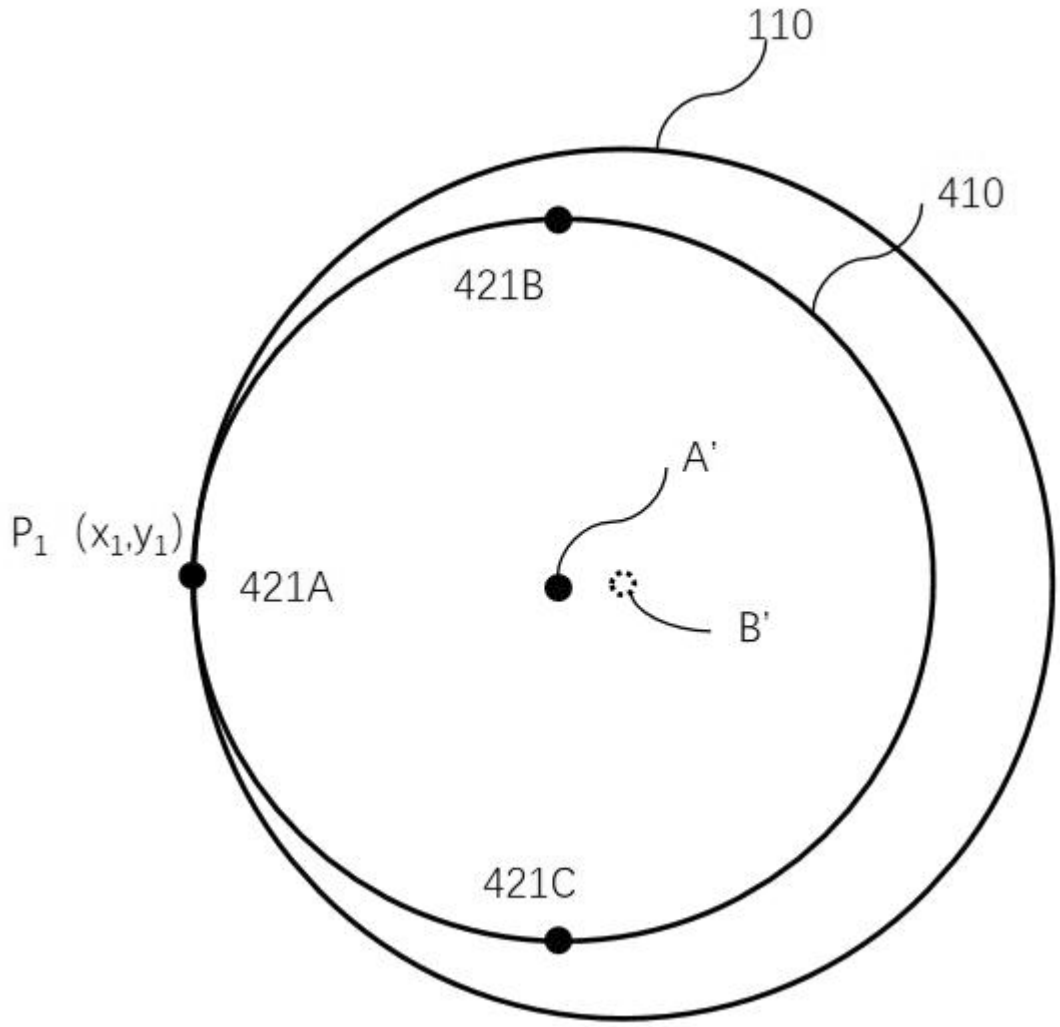


FIG 7a

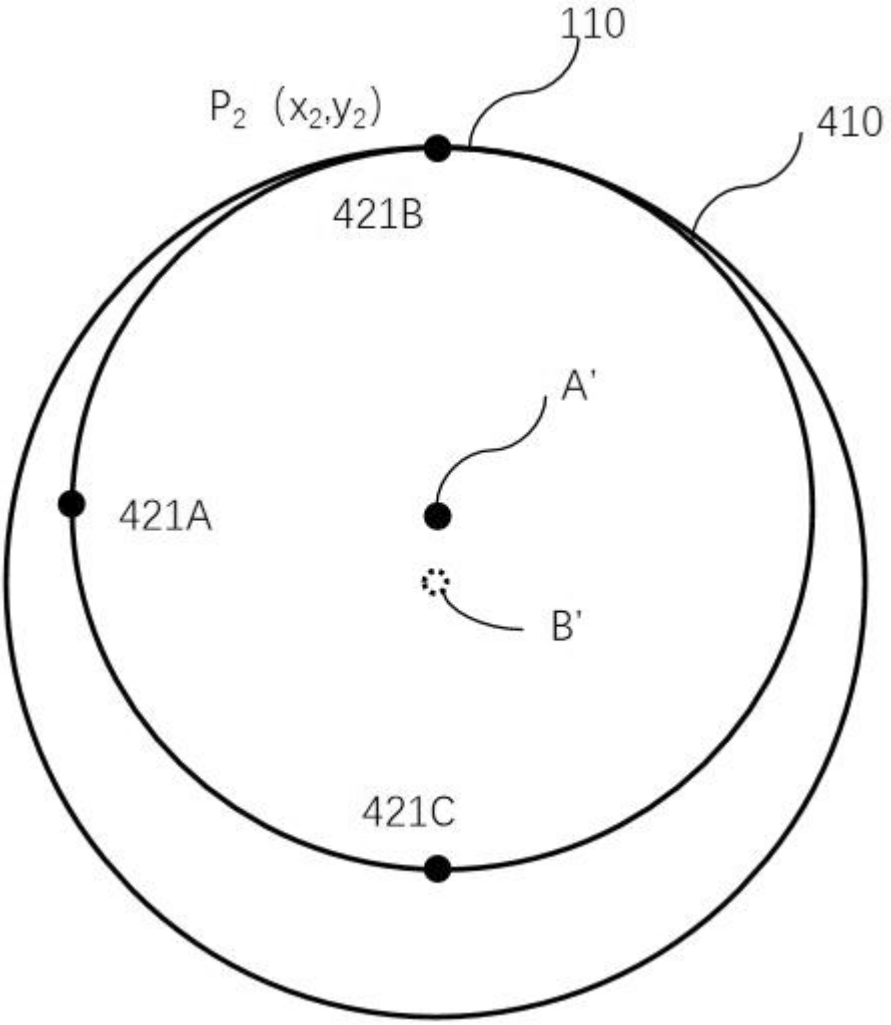


FIG 7b

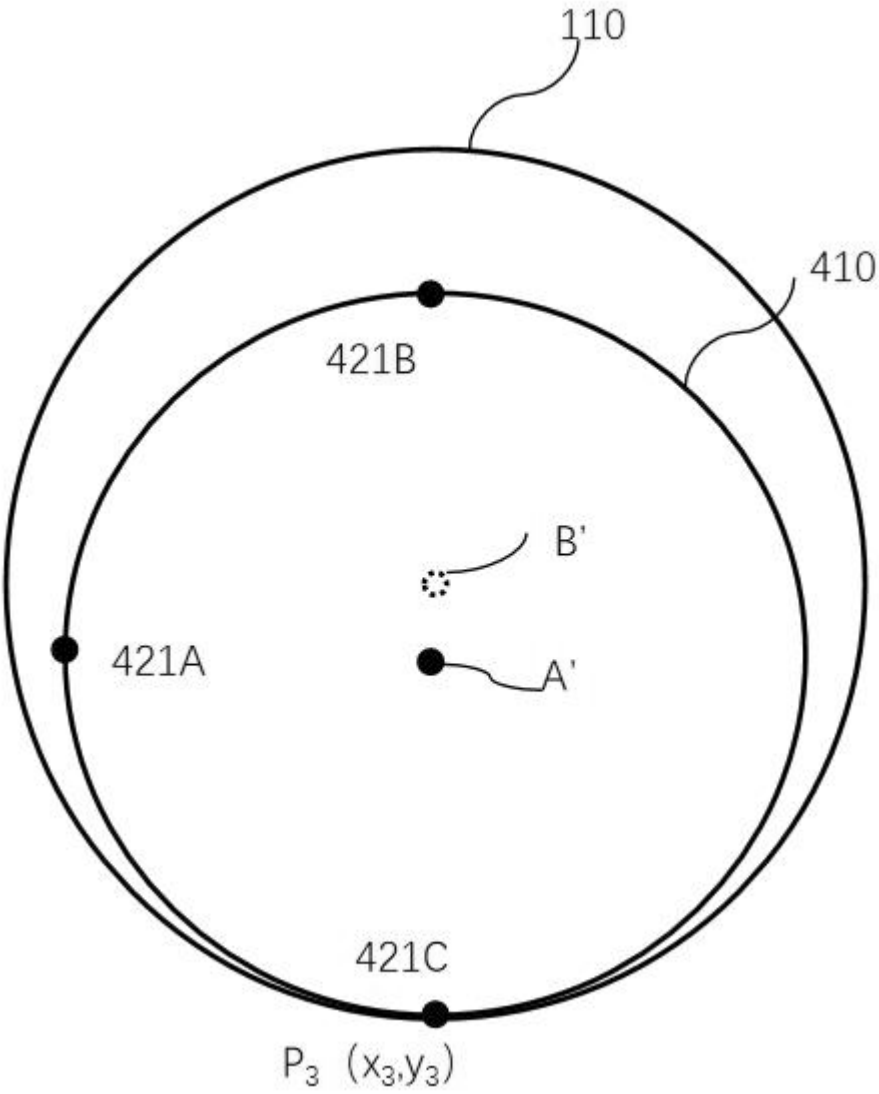


FIG 7c